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 Member of the Texas Instruments Widebus™ Family 	DGG OR DL PACKAGE (TOP VIEW)
 EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process 	1 <u>OEAB</u> 1 56 1 <u>OEBA</u> 1LEAB 2 55 1LEBA
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1CEAB 2 55 1CEBA 1CEAB 3 54 1CEBA GND 4 53 GND
 Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} = 3.3 V, T_A = 25°C 	1A1 [5 52] 1B1 1A2 [6 51] 1B2
 Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17 	V _{CC} [7 50] V _{CC} 1A3 [8 49] 1B3
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors 	1A4 [9 48] 1B4 1A5 [10 47] 1B5 GND [11 46] GND
 Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages 	1A6 [12 45] 1B6 1A7 [13 44] 1B7 1A8 [14 43] 1B8
description	2A1 [15 42] 2B1 2A2 [16 41] 2B2
This 16-bit registered transceiver is designed for low-voltage (3.3-V) V_{CC} operation.	2A3 17 40 2B3 GND 18 39 GND 2A4 19 38 2B4
The SN74LVC16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate	2A5
latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.	V _{CC} [22 35] V _{CC} 2A7 [23 34] 2B7 2A8 [24 33] 2B8 GND [25 32] GND
direction of data now.	GND 25 32 GND

The A-to-B enable (\overline{CEAB}) input must be low in order to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low,

22	35 U VCC
23	34 🛛 2B7
24	33 🛛 2B8
25	32 🛛 GND
26	31 2CEBA
27	30 2LEBA
28	29 20EBA
	25 26 27

the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVC16543 is characterized for operation from -40°C to 85°C.



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FUNCTION TABLE[†] (each 8-bit section)

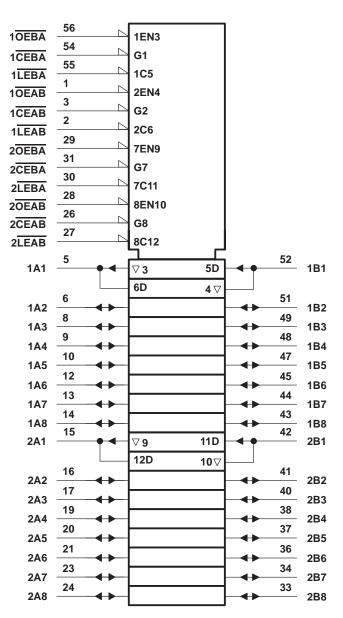
(caon o bit cootion)							
	INPU	IPUTS OUTPL					
CEAB	LEAB	OEAB	Α	В			
Н	Х	Х	Х	Z			
Х	Х	Н	Х	Z			
L	Н	L	Х	в ₀ ‡			
L	L	L	L	L			
L	L	L	Н	Н			

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

[‡] Output level before the indicated steady-state input conditions were established



logic symbol[†]

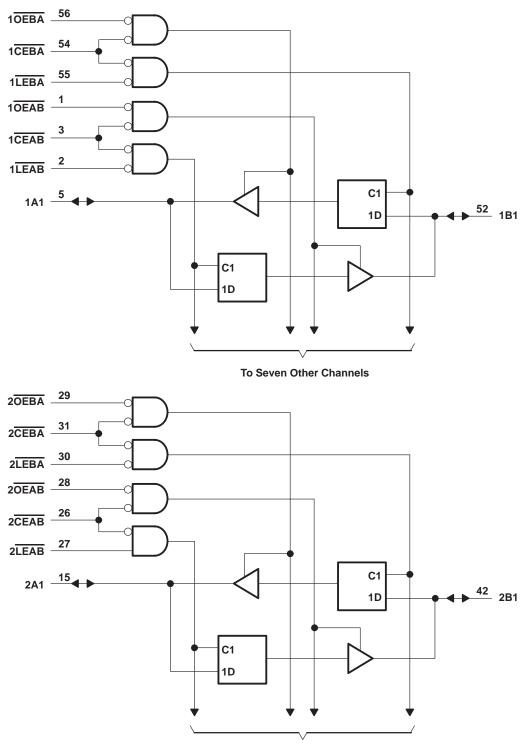


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I : Except I/O ports (see Note 1) I/O ports (see Notes 1 and 2) Output voltage range, V_O (see Notes 1 and 2) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DGG package DL package	$\begin{array}{cccc} & -0.5 \ V \ to \ 4.6 \ V \\ 0.5 \ V \ to \ V_{CC} \ + \ 0.5 \ V \\ 0.5 \ V \ to \ V_{CC} \ + \ 0.5 \ V \\ & -50 \ mA \\ & & \pm 50 \ mA \\ & & & \pm 50 \ mA \\ & & & & \pm 100 \ mA \\ & & & & & 1 \ W \end{array}$
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This value is limited to 4.6 V maximum.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	V
VIH	High-level input voltage	$V_{CC} = 2.7 V \text{ to } 3.6 V$	2		V
VIL	Low-level input voltage	$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8	V
VI					V
Vo	Output voltage		0	VCC	V
	High-level output current $\frac{V_{CC} = 2.7 \text{ V}}{V_{CC} = 3 \text{ V}}$		-12	mA	
ЮН		$V_{CC} = 3 V$		-24	IIIA
	Low-level output current	$V_{CC} = 2.7 V$		12	mA
10L	V _{CC} = 3 V			24	ША
$\Delta t/\Delta v$	Input transition rise or fall rate	r fall rate		10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CON	DITIONS	Vcc [†]	MIN T	YP [‡] MAX	UNIT	
		I _{OH} = -100 μA		MIN to MAX	V _{CC} -0.2			
Maria				2.7 V	2.2		V	
VOH		$I_{OH} = -12 \text{ mA}$		3 V	2.4		V	
		I _{OH} = -24 mA		3 V	2			
		I _{OL} = 100 μA		MIN to MAX		0.2		
VOL		I _{OL} = 12 mA I _{OL} = 24 mA		2.7 V		0.4	V	
				3 V		0.55		
lj –	Control inputs	V _I = V _{CC} or GND		3.6 V		±5	μA	
1	A an D manta	V _I = 0.8 V		2.14	75		μΑ	
ll(hold)	A or B ports	V _I = 2 V		3 V	-75			
IOZ§	-	V _O = V _{CC} or GND		3.6 V		±10	μΑ	
ICC		$V_{I} = V_{CC} \text{ or GND},$ I	O = 0	3.6 V		40	μA	
∆ICC		One input at V _{CC} – 0.6 V, C	Other inputs at V _{CC} or GND	3 V to 3.6 V		500	μA	
Ci	Control inputs	V _I = V _{CC} or GND		3.3 V		3	pF	
Cio	A or B ports	V _O = V _{CC} or GND		3.3 V		7	pF	

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] All typical values are at V_{CC} = = 3.3 V, T_A = 25°C. § For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 3.3 ± 0.3 V		V _{CC} = 2.7 V		UNIT
		MIN	MAX	MIN	MAX	
tw	Pulse duration, LE or CE low	4		4		ns
t _{su}	Setup time, Data before LE, CE	2		2		ns
t _h	Hold time, Data after LE, CE	2		2		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

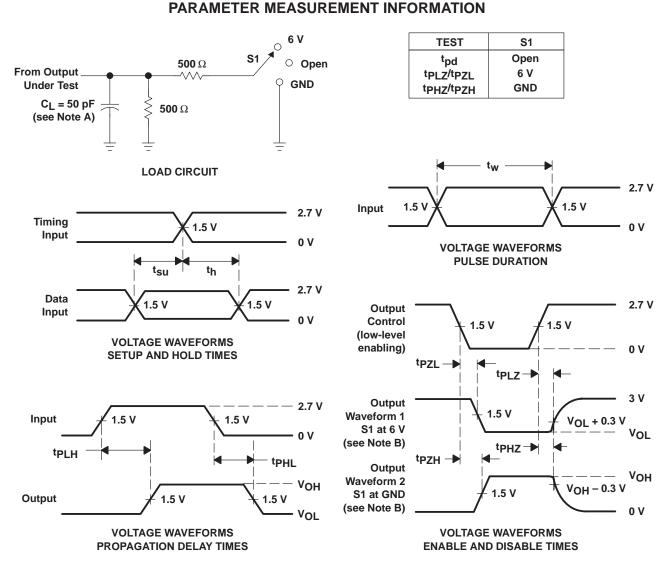
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	
^t pd	A or B	B or A	1.5	8	1.5	9	ns
^t pd	LE	A or B	1.5	9	1.5	10	ns
ten	CE	A or B	1.5	9	1.5	10	ns
^t dis	CE	A or B	1.5	9	1.5	10	ns
ten	OE	A or B	1.5	8.5	1.5	9.5	ns
^t dis	OE	A or B	1.5	8.5	1.5	9.5	ns



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operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER		TEST CO	TYP	UNIT		
	Outputs enabled		21	~ [
Cpd	C _{pd} Power dissipation capacitance per transceiver	Outputs disabled	C _L = 50 pF, f =	f = 10 MHz	3.5	рF



NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns. D. The outputs are measured one at a time with one transition per measurement.

- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as t_{en} .
- G. tpLH and tpHL are the same as t_{pd} .



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